

# Potential of Thin Film Detectors

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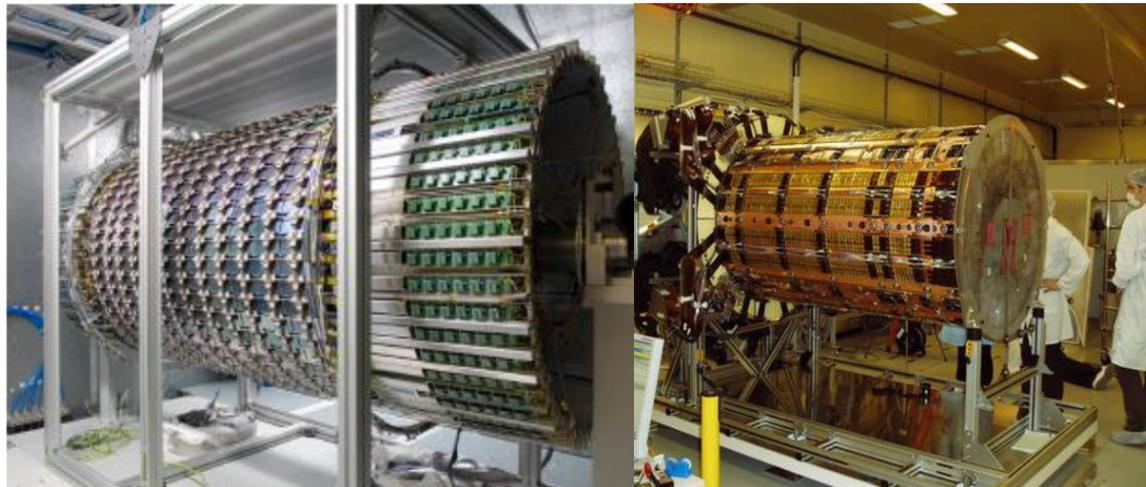
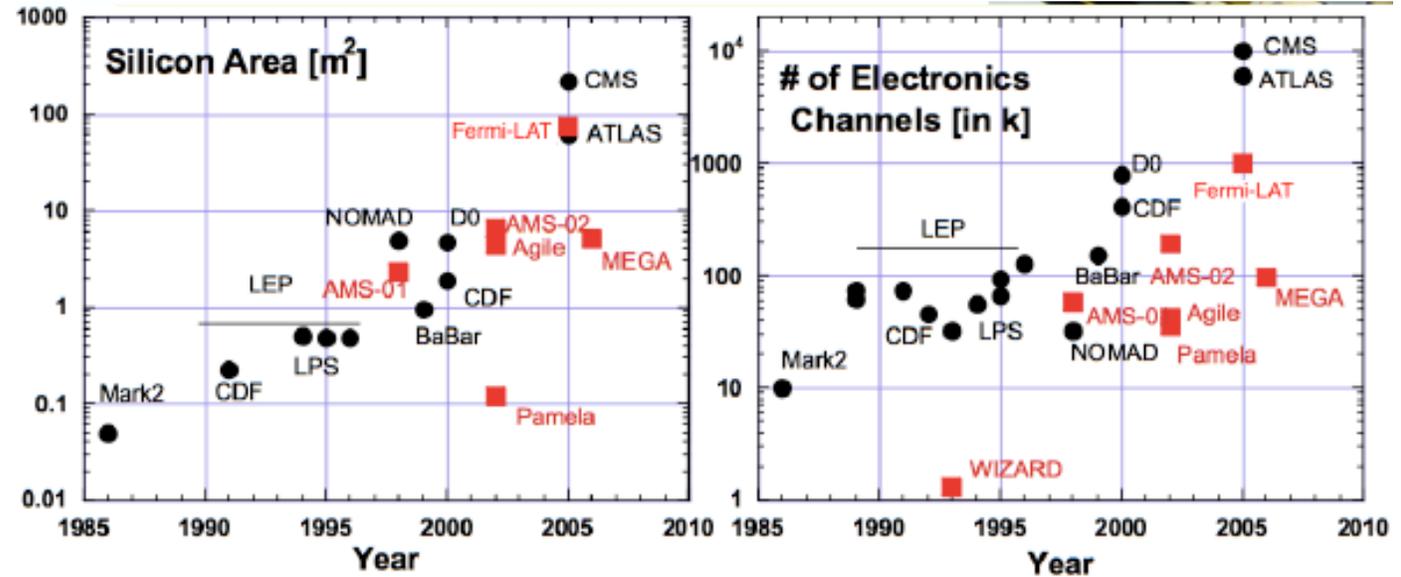
# Motivation

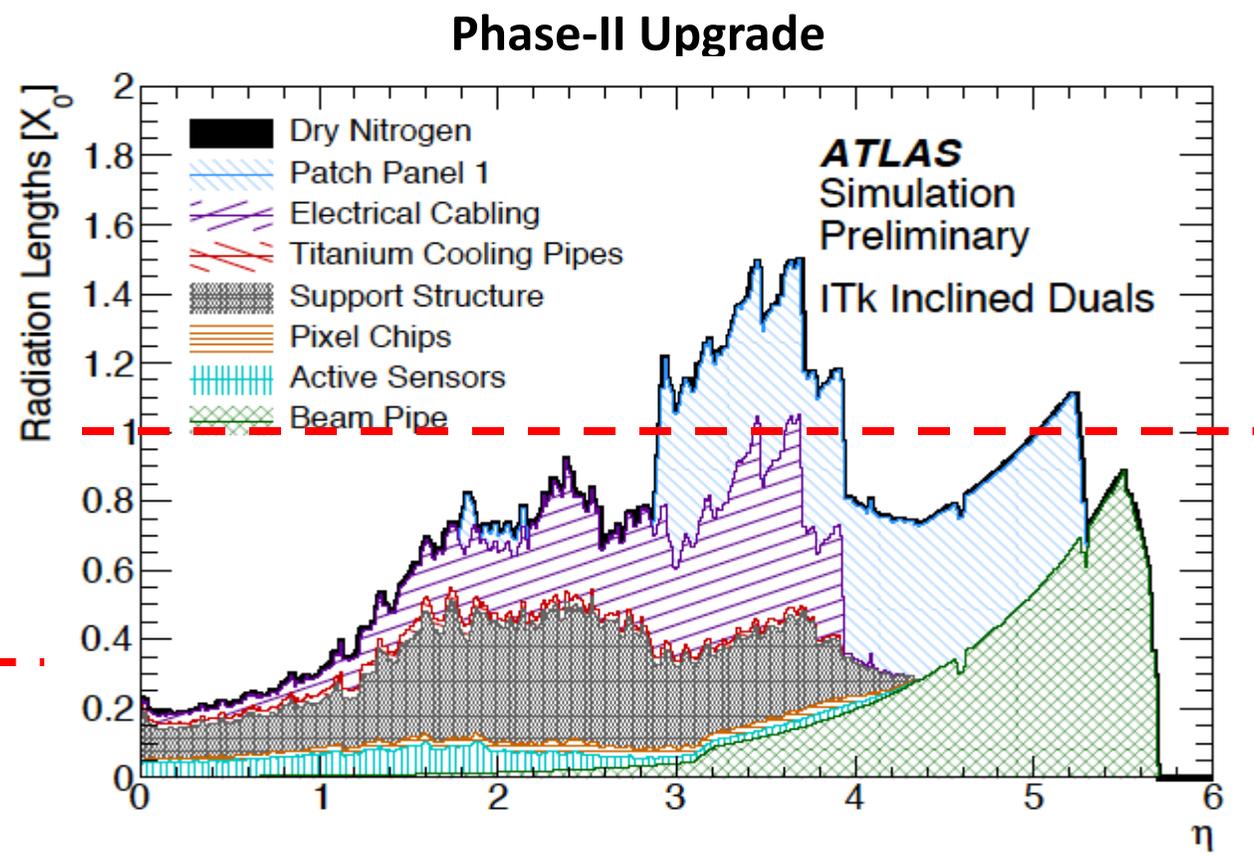
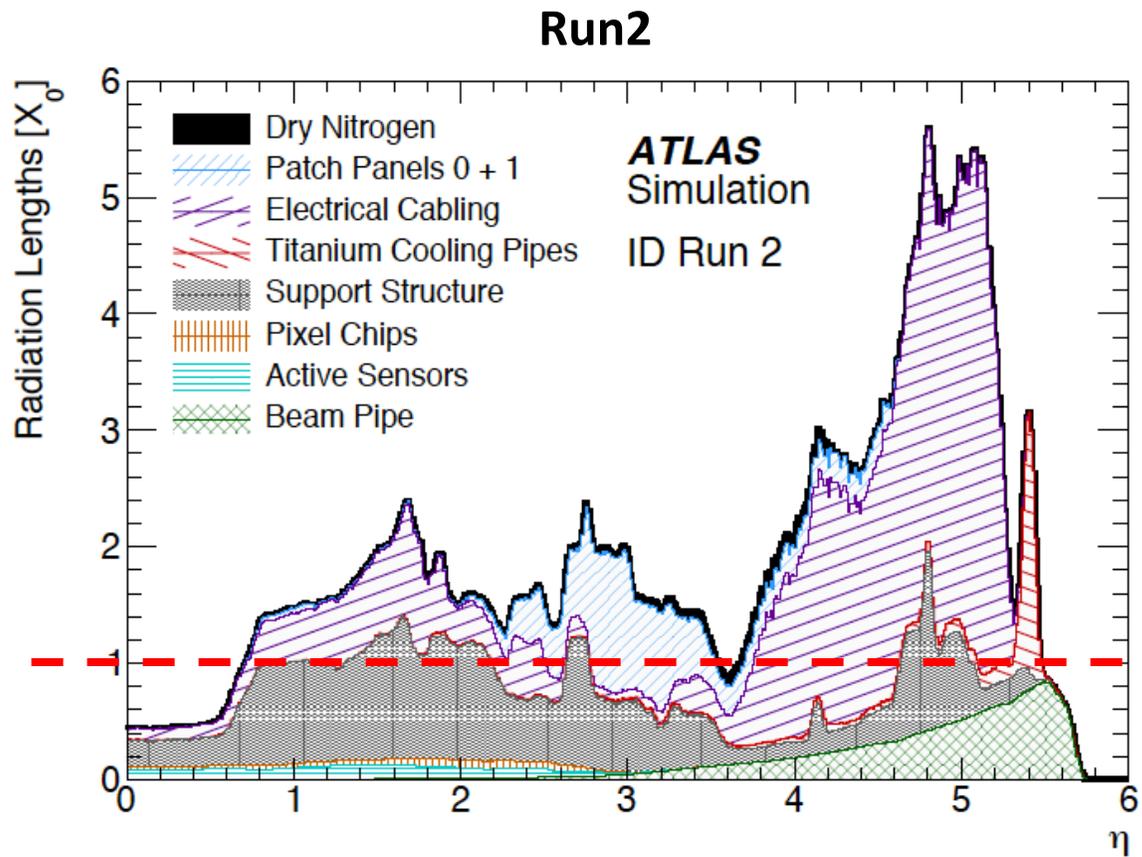
Silicon detectors are a cornerstone of High Energy Physics

Larger fractions of detectors are made with silicon

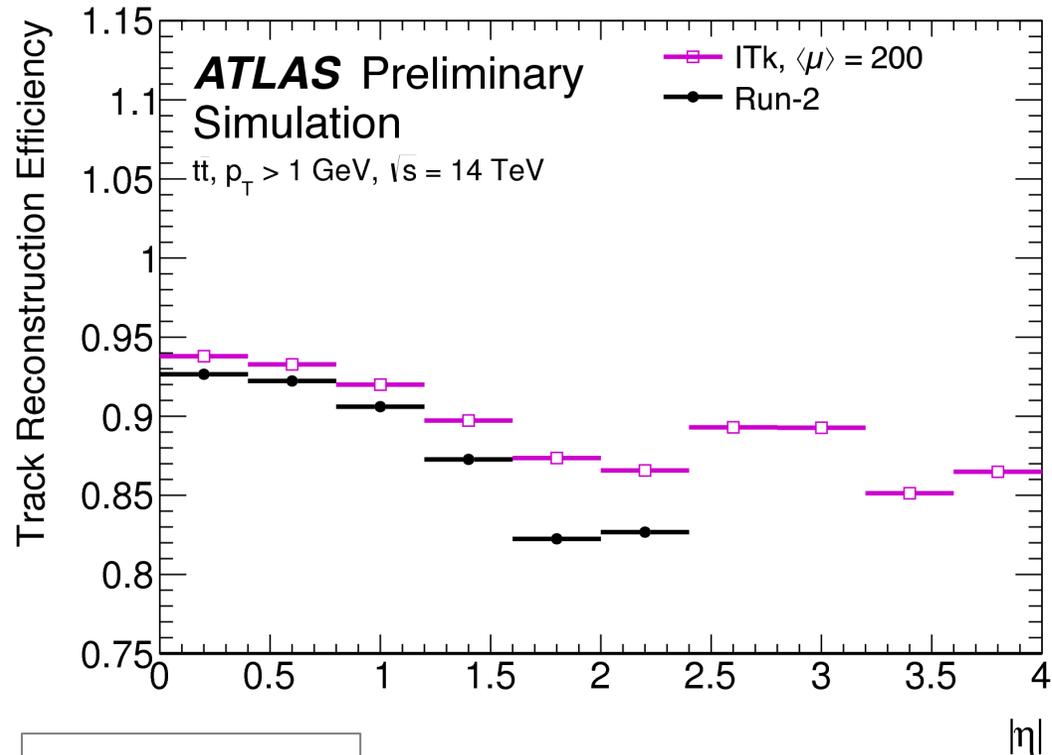
- More layers for precise tracking
- Limiting factor is often the cost
- Shift toward high precision silicon calorimeters

*Can we come up with an alternative that might have an advantage?*

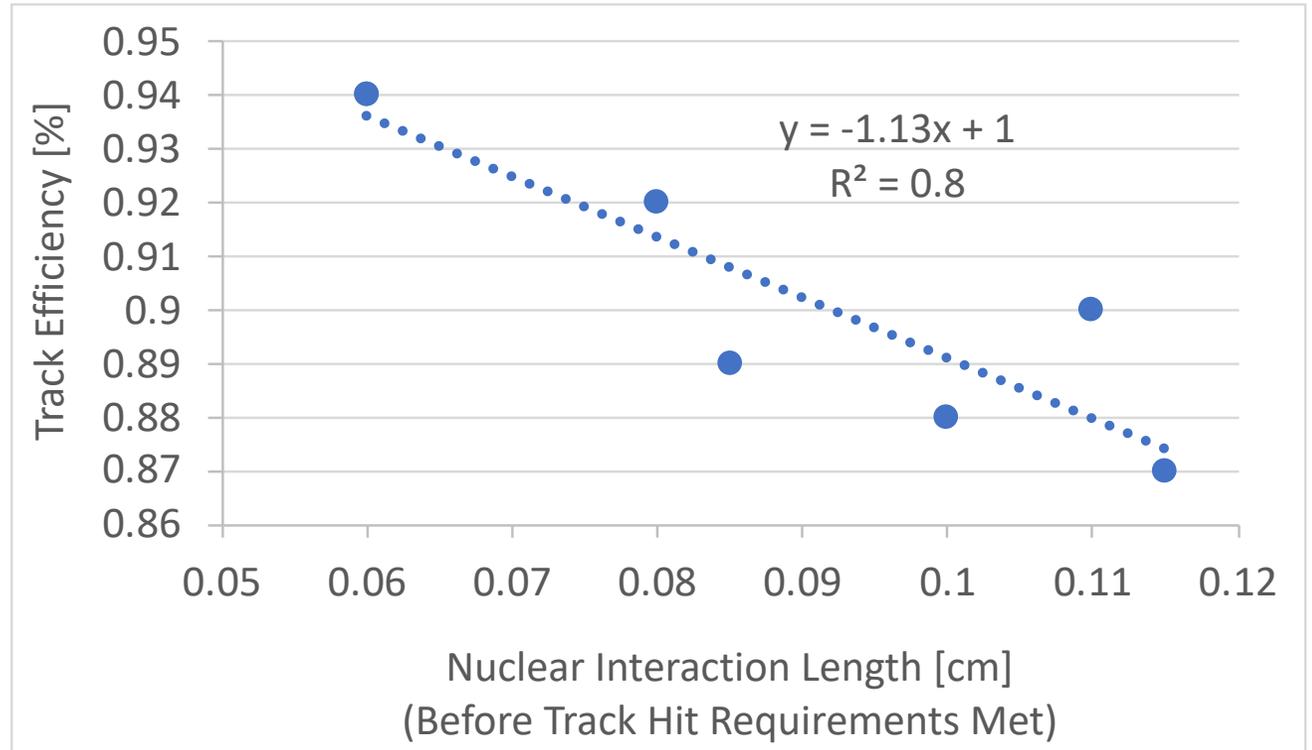




- Tremendous progress since the original ATLAS
- Target support structures & services
- Continue this trend



ATLAS-TDR-030



- A single silicon sensor has very high intrinsic tracking efficiency > 99%
- A detector system, however, is limited by the dead material
- Overall tracking efficiency can be optimized by reducing dead material

- **Low Mass**
- **Low power**
- **High position resolution**
- **Fast timing resolution**
- **Monolithic**
- **Radiation Tolerance**
  
- **Energy resolution**
- **Energy range: signal/noise**
  - **Low electron energies**
  
- **Low cost**
- **Reduce services**
- **Reduce cooling needs**
  
- **All-in-one?**
  - **Fewer 'sub-systems'**
    - **Reduce cost**
    - **Optimize resources**
  
- **Faster development cycle**

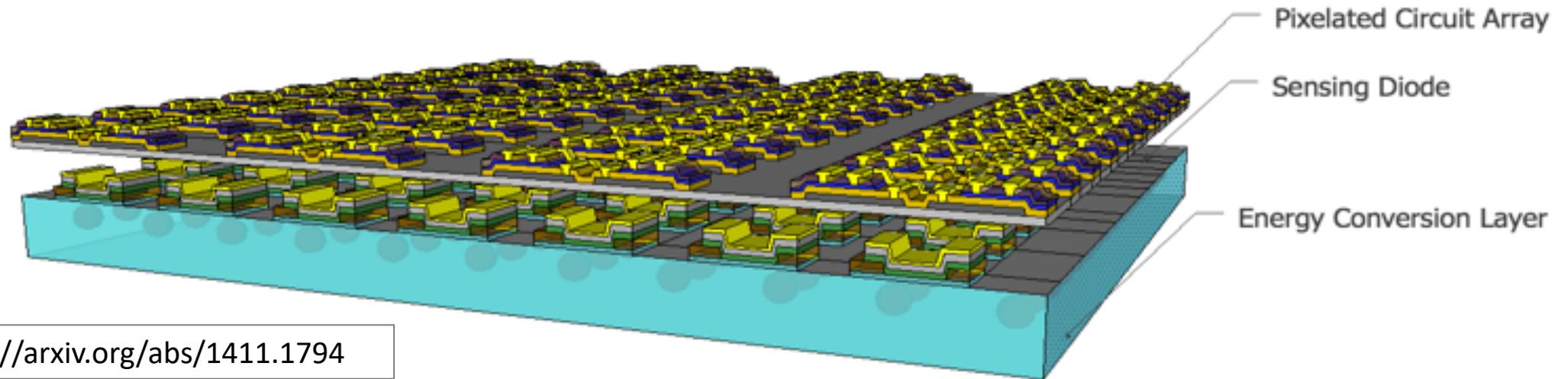
**How many features can we combine into one detector technology?**

Thin Films: thin layers of materials ranging from nm to  $\mu\text{m}$

- Current popular applications
  - solar cells
  - LCD screens
- Thin Films for Particle Detectors:
  - Thin Film Diodes + Thin Film Transistors

Potential:

- Large area 'printing'
- Low mass
- Low cost
- Pixelated
- Integrated/monolithic design



<https://arxiv.org/abs/1411.1794>

# Thin Film Detectors: Materials

- Many potential materials with promising properties
- Catalogue potential material candidates
  - Fabrication techniques
  - Key performance parameters
  - Challenges related to individual materials

Material	$Z$	$\rho$ (g/cm <sup>3</sup> )	$\frac{-dE}{dx}$ [MeV/(g/cm <sup>2</sup> )]	MIP in 10 $\mu$ m (keV)	$E_i$ (eV)	$\langle N_{e-h \text{ pairs}} \rangle$ in 10 $\mu$ m
Diamond	6	3.51	1.78	6.25	13	0.5k
Si	14	2.329	1.664	3.9	3.62	1.1k
CdS	32	4.8	4.0*	19.08	6.49*	2.9k
PbS	49	7.6	6.2*	46.8	1.98*	23.6k
ZnO	19	5.6	4.4*	24.8	8.25*	3.0k
GaAs	32	5.32	1.4	7.45	4.2	1.8k
InP	32	4.97	4.0*	20.5	4.2	4.8k
HgI	66.5	6.4	5.6*	35.8	4.3	8.3k
InSb	50	5.78	4.9*	28.1	1.57*	17.9k
InAs	41	5.67	4.7*	26.8	1.94*	13.8k
HgTe	66	8.1	6.7*	54.7		
CdZnTe	43.3	6	5.0*	29.8	4.7	6.3k
IGZO	29.5	6			7.58*	

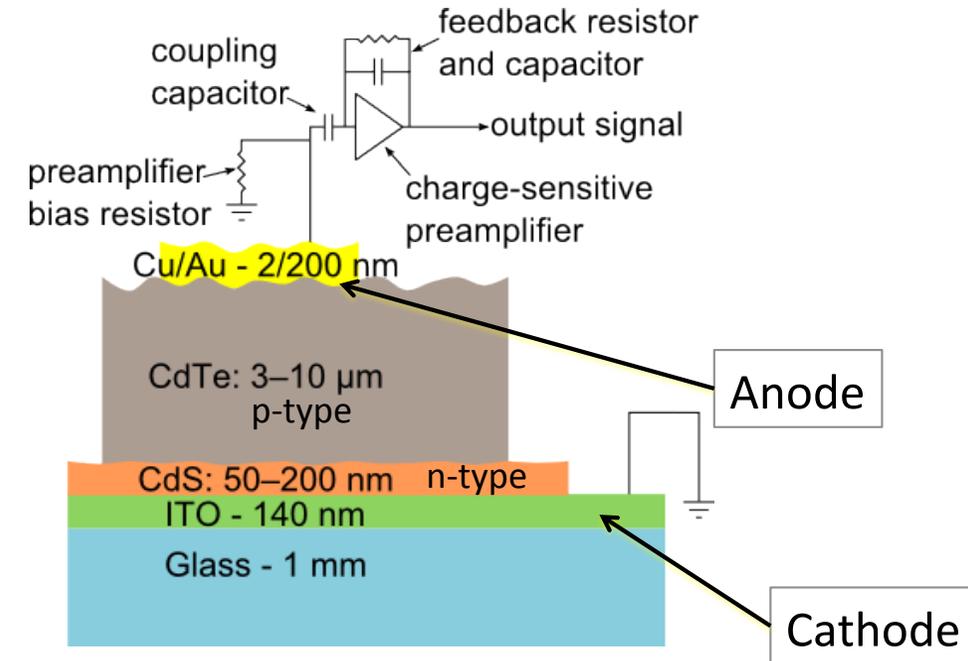
\*calculated

Material	$\mu_e$ ( $\frac{cm^2}{V \cdot s}$ )	$\mu_h$ ( $\frac{cm^2}{V \cdot s}$ )
Diamond	1800	1200
Si	1350	480
CdTe	1050	100
CdS	340	50
PbS	600	700
ZnO	130	
IGZO	15	0.1
GaAs	8000	400
InP	4600	150
HgI	100	4
InSb	78000	750
InAs	33000	460
HgTe	22000	100
CdZnTe	1350	120

<https://arxiv.org/abs/1411.1794>

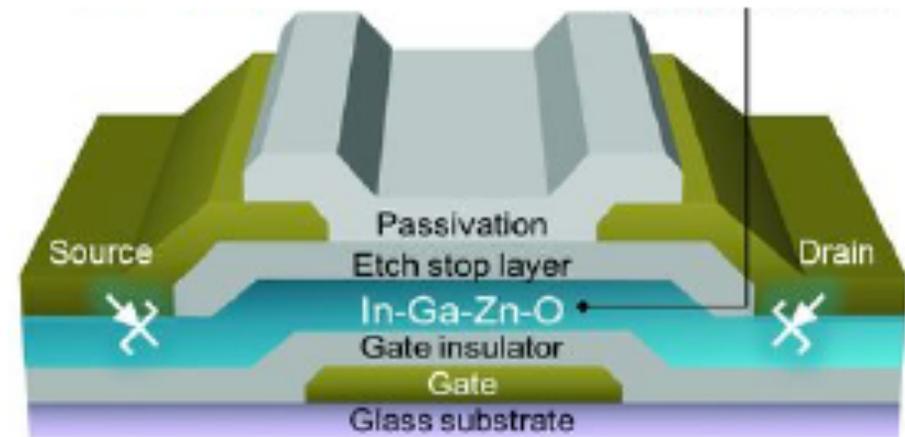
## Thin Film (TF) Fabrication

- Films are grown in thin layers on a substrate with high precision
- Compare to traditional silicon that relies on growing a large crystal and then drilling, etching, etc.
- Thin Films can be fabricated using
  - chemical bath deposition
  - close-space sublimation
  - Atomic layer deposition
- TF's can be grown at least 200  $\mu\text{m}$  thick (not standard)
- Certain types of Thin Film fabrication are much less expensive
  - $< \$10$  per  $\text{m}^2$  for a 2.5  $\mu\text{m}$  thick CdTe film
- TF can be deposited on flexible substrates such as organic polymers and plastics



- Services is a large part of the dead material
- Low power electronics can help
- Thin Film Transistors is a large area of nanoscience development
- Explore options for HEP
  - Example:
    - High gains  $> 400$
    - Low power  $< 1$  nW
    - Potential integration in thin film detector

## Thin Film Transistors (TFTs): Ultralow Power



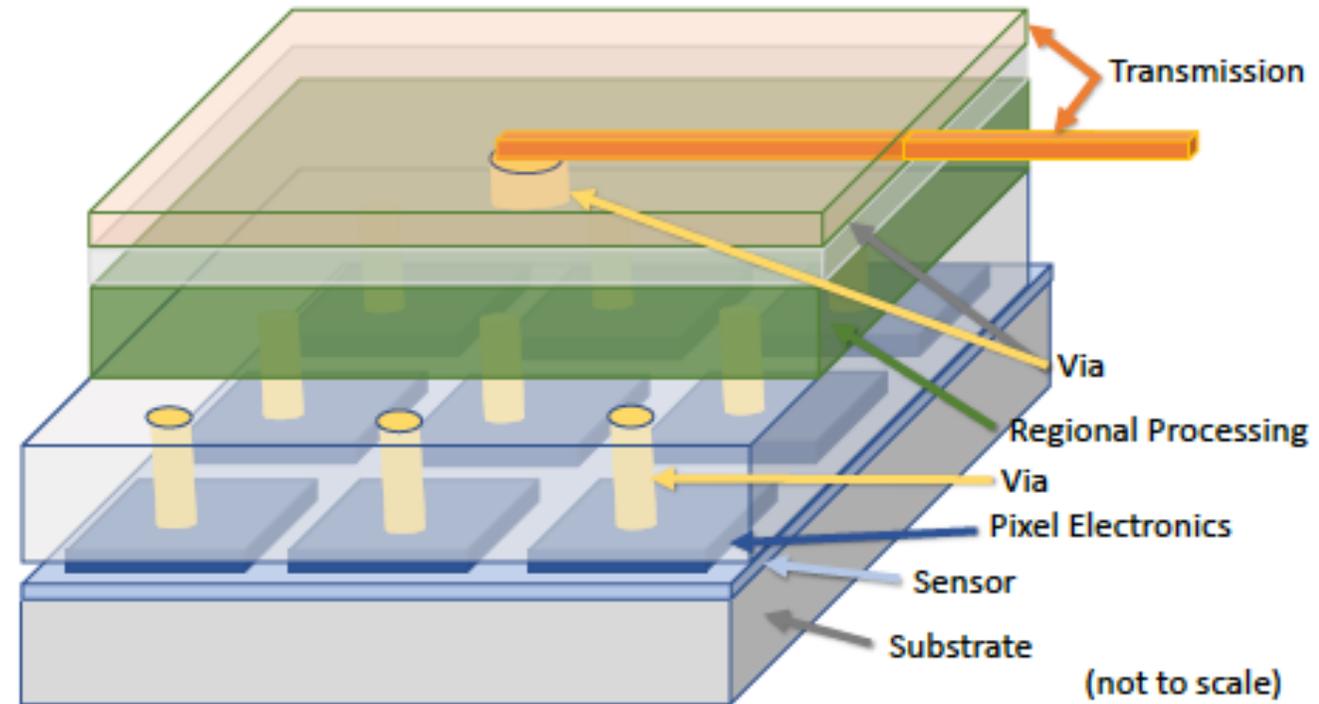
Sungsik Lee and Arokia Nathan. Subthreshold Schottky-barrier thin-film transistors with ultralow power and high intrinsic gain. *Science*, 354(6310):302-304, 2016.

# Thin Film Detectors

- Combine thin film layers into a complete detector
- Consider thin film deposition techniques
  - Potential to be large area low cost like LCD screens
- Options for many different semiconductor materials
- Potential for monolithic integration of sensor + electronics
- Minimize services radiation length
- $< 1\% X/X_0$

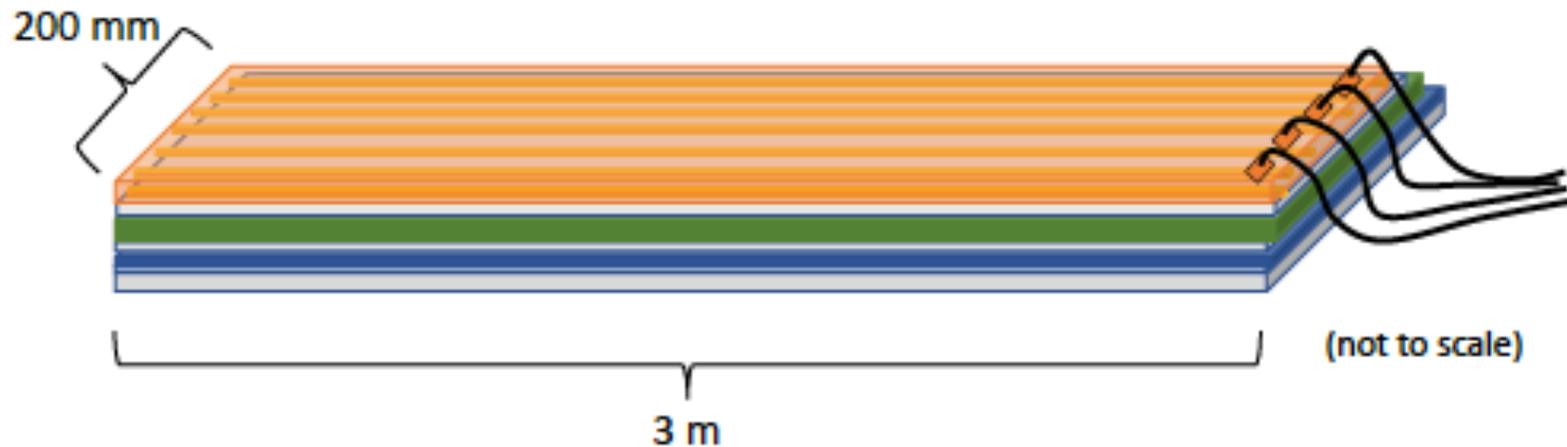
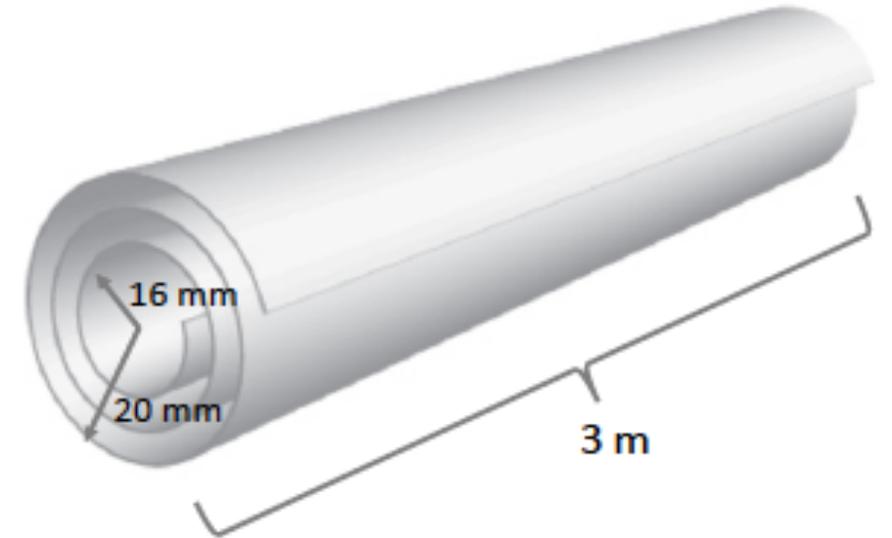
Layer	Material	thickness [ $\mu\text{m}$ ]	$X_0$ [cm]	$X/X_0$	$\lambda_0$ [cm]	$\lambda/\lambda_0$
Substrate	PET	250	29	0.088%	60.6	0.041%
Sensor	InSb	10	15	0.0065%	46.8	0.0021%
Electronics	InGaZnO	200	10	0.20%	45.0	0.044%
1st Via	Cu/dielectric	100	29	0.035%	60.2	0.017%
Electronics	InGaZnO	200	10	0.20%	45.0	0.044%
2nd Via	Cu/dielectric	100	25	0.04%	51.2	0.020%
Transmission	Cu/dielectric	250	20	0.13%	45.4	0.055%
<b>Total</b>				<b>0.70%</b>		<b>0.22%</b>

Thin Film Detector Layers:



Large area design possibilities:

- Fabricate on a single flexible substrate
- Creative detector geometries like spiral cylinder roll
- Simplify detector construction process
- Move toward a single active detector system



## Key Challenges:

- Sensor performance
  - Want to match silicon sensor performance
- Transistor designs
  - Compatible fabrication processes on top of sensor
  - Transistor footprint
- Vertical integration
  - How to reliably stack layers
  - Over large areas
- Transmission signal integrity over long distances
- Radiation damage
- Process industrialization

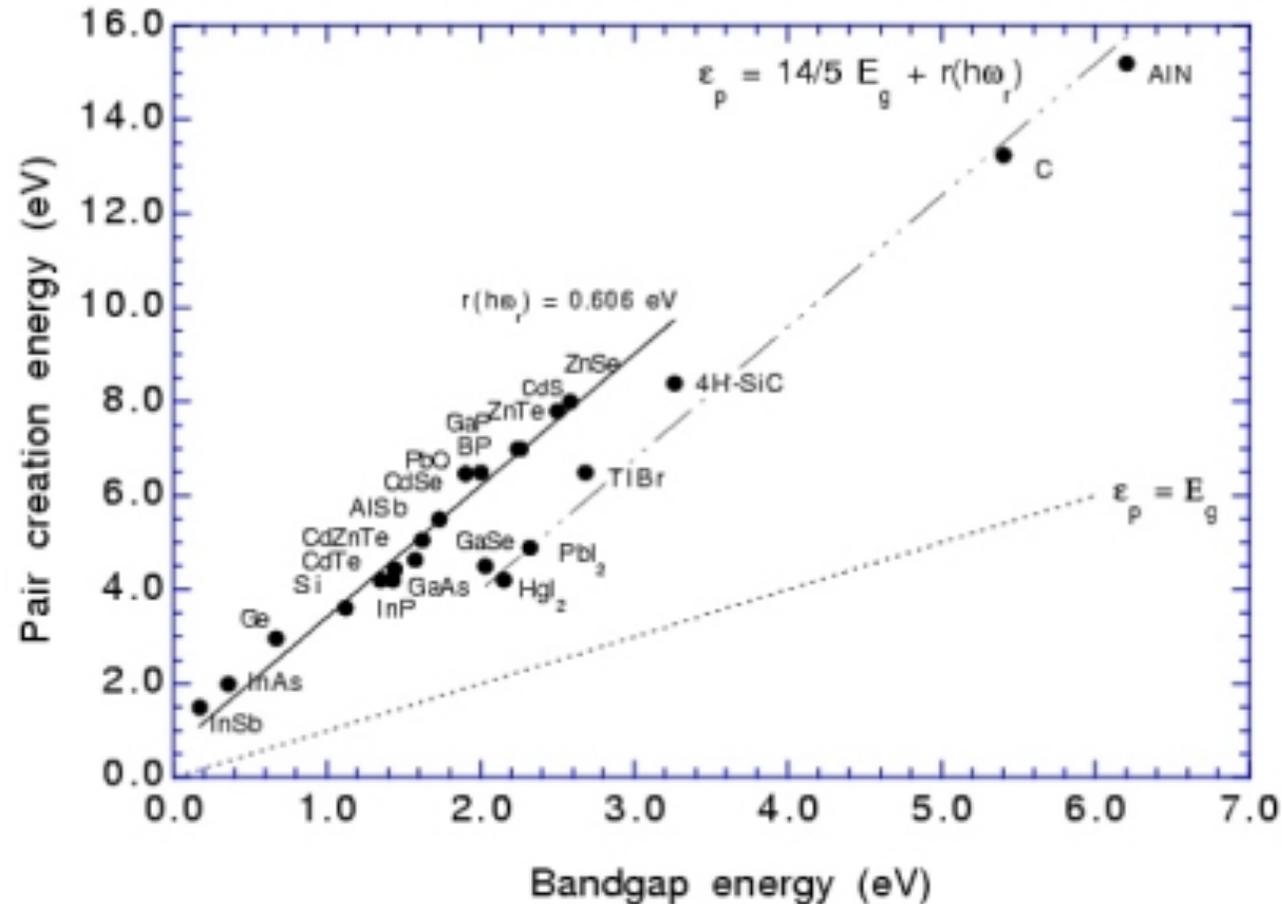
## Potential of a Thin Film Detector design:

- Material level understanding to design and optimize a given detector design for a specific application
  - Tracking efficiency
  - Timing resolution
  - Energy resolution
  - Occupancy
  - Radiation damage
  - Etc.
- Simplify fabrication techniques to follow industrial standards
  - Large area
  - 'Printable' designs
  - monolithic
  - Low cost
  - Fast turn-over cycle
- A lot of unknowns to realize the full potential → Long-term blue-sky R&D
- Interesting path to see where it leads

## Backup

Use the bandgap energy,  $E_g$ , to estimate  $E_i$ :  $E_i \propto E_g$

$$E_i \approx 2.0877 \cdot E_g + 1.2122$$



Material	$E_g$ (eV)	$E_i$ (eV)
Ge	0.67	2.96
Si	1.11	3.62
CdTe	1.4	4.43
GaAs	1.43	4.2
diamond	5.5	13

## Design Goals

Meet current tracking performance of a typical tracking detector such as ATLAS

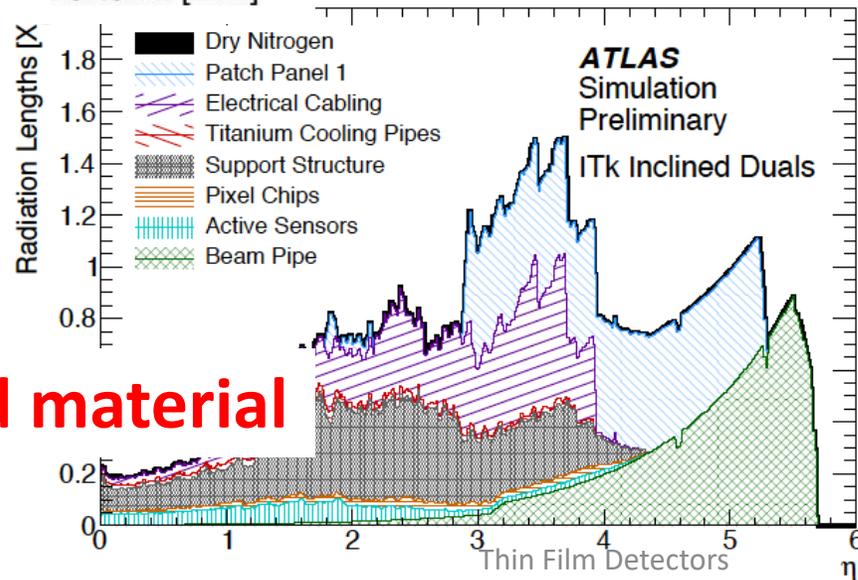
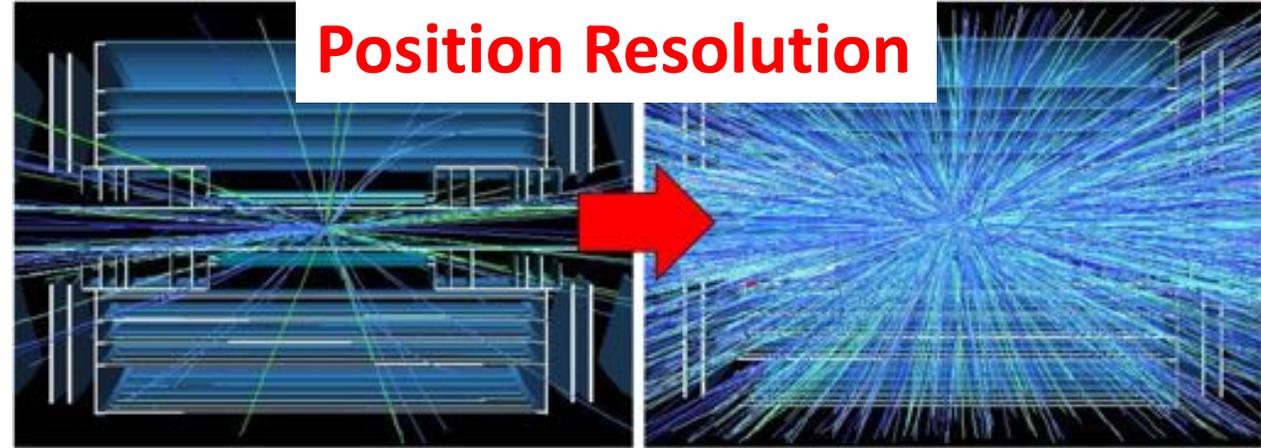
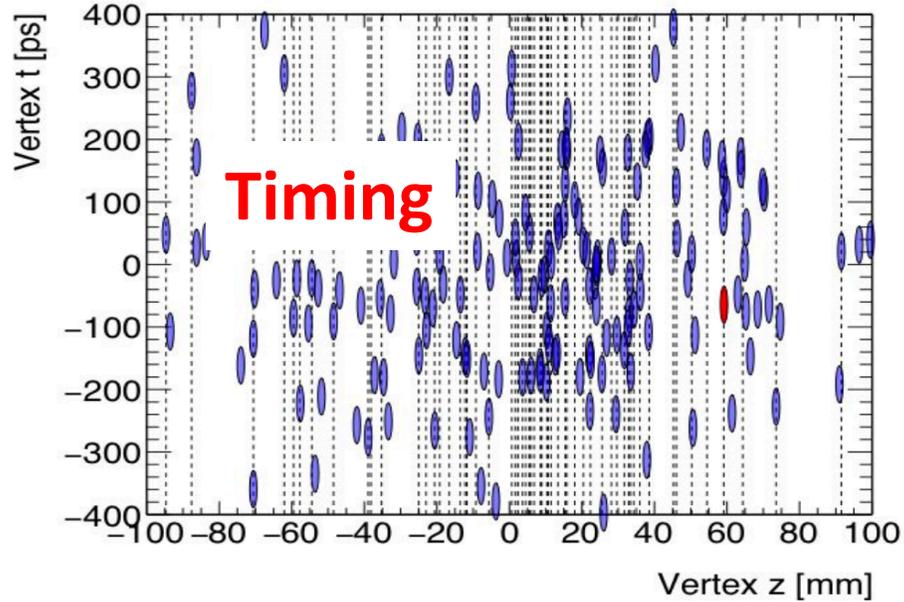
- Charge yield 1,000 – 10,000 electrons
- Energy resolution 5-10%
- Position resolution  $\sim 45 \mu\text{m}$
- Timing resolution 25 ns
- Signal/Noise  $\sim 20$

Other applications: ILC

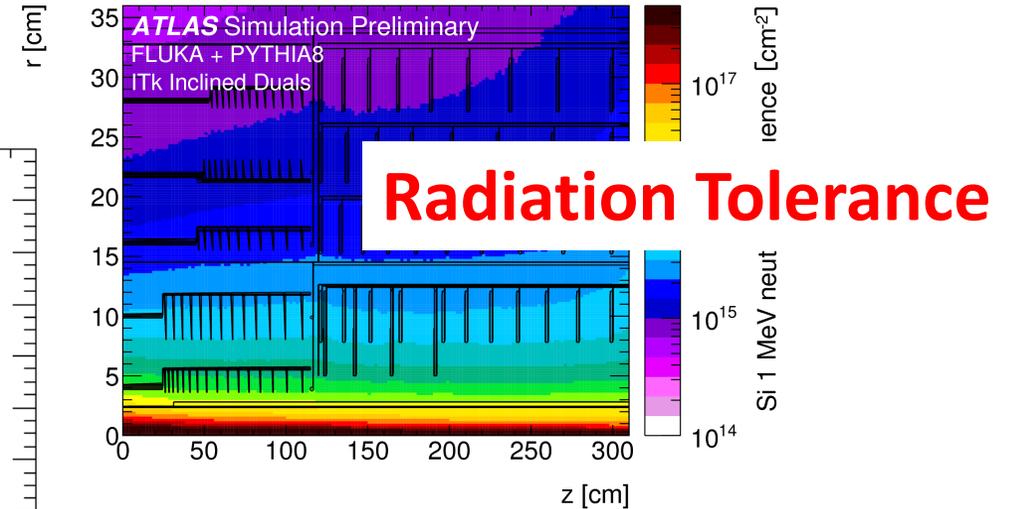
- Timing resolution 5 ns
- Tracking precision  $3 \mu\text{m}$
- $0.1\% X_0$
- $\sim 10^{14} \text{ 1 MeV } N_{\text{eq}}/\text{cm}^2$



Flexible layers “printed” in large sheets  
→ Possibility for unique geometries with less dead space



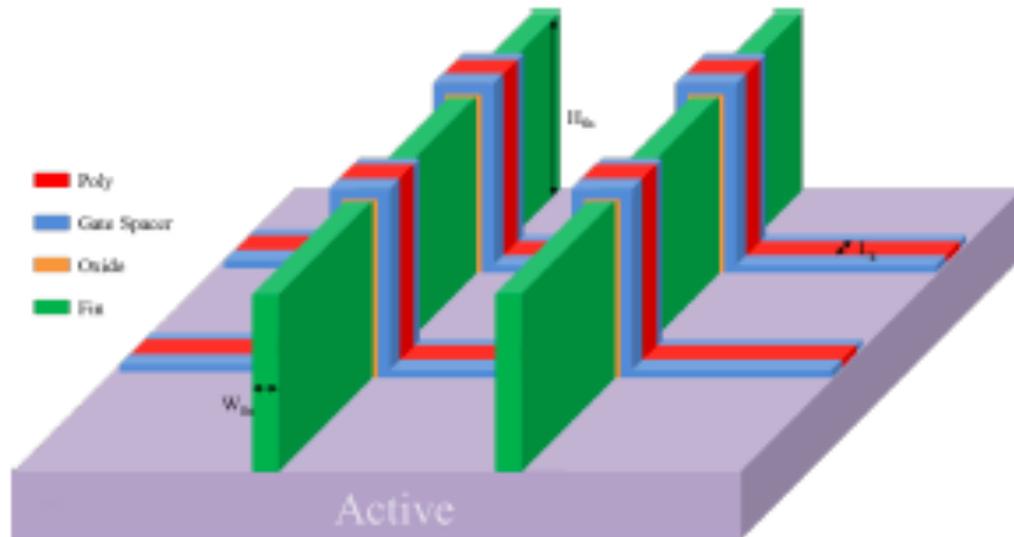
**Low mass/dead material**



**...Typical of large accelerator experiments**

- FinFETs
  - ~30% less power than CMOS
  - Faster switching times
  - Energy harvesting interfaces
    - 'self-powering'
    - Can we take advantage?

## FinFETs

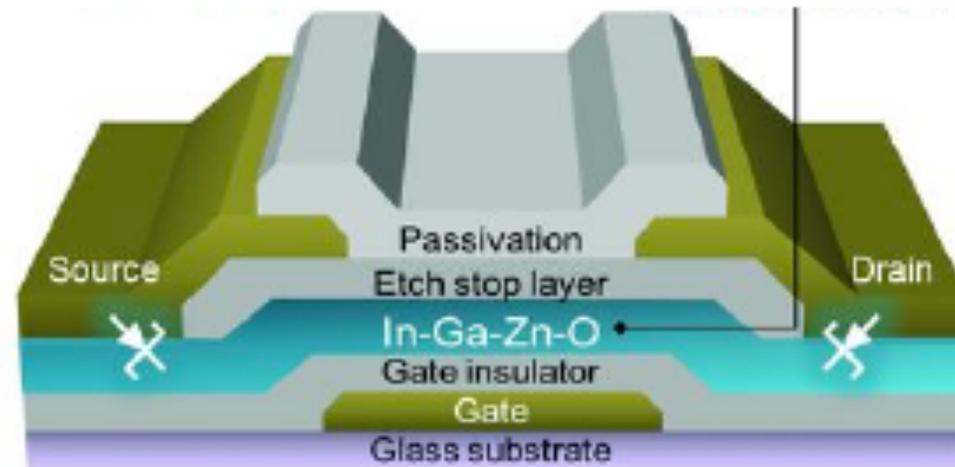


Katrine Lundager, Behzad Zeinali, Mohammad Tohidi, Jens K. Madsen, and Farshad Moradi. Low Power Design for Future Wearable and Implantable Devices. *J. Low Power Electron. Appl.*, 6(64):20, 2016.

3/18/21

- TFTs
  - High gains  $> 400$
  - Low power  $< 1$  nW
  - Potential integration in thin film detector

## Thin Film Transistors (TFTs)



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